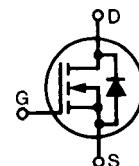


Standard Power MOSFET

IRFP 260

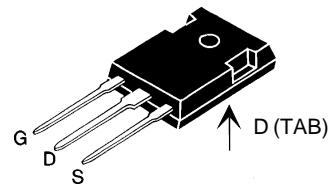
V_{DSS} = 200 V
 $I_{D(\text{cont})}$ = 46 A
 $R_{DS(\text{on})}$ = 55 mΩ

N-Channel Enhancement Mode



Symbol	Test Conditions	Maximum Ratings		
V_{DSS}	$T_J = 25^\circ\text{C}$ to 150°C	200		V
V_{DGR}	$T_J = 25^\circ\text{C}$ to 150°C ; $R_{GS} = 1 \text{ M}\Omega$	200		V
V_{GS}	Continuous	± 20		V
V_{GSM}	Transient	± 30		V
I_{D25}	$T_c = 25^\circ\text{C}$	46		A
I_{DM}	$T_c = 25^\circ\text{C}$, pulse width limited by T_{JM}	184		A
I_{AR}		46		A
E_{AR}	$T_c = 25^\circ\text{C}$	28		mJ
dv/dt	$I_s \leq I_{DM}$, $di/dt \leq 100 \text{ A}/\mu\text{s}$, $V_{DD} \leq V_{DSS}$, $T_J \leq 150^\circ\text{C}$, $R_G = 2 \Omega$	5		V/ns
P_D	$T_c = 25^\circ\text{C}$	280		W
T_J		-55 ... +150		°C
T_{JM}		150		°C
T_{stg}		-55 ... +150		°C
M_d	Mounting torque	1.13/10	Nm/lb.in.	
Weight		6		g
Maximum lead temperature for soldering 1.6 mm (0.062 in.) from case for 10 s		300		°C

TO-247 AD



G = Gate, D = Drain,
S = Source, TAB = Drain

Symbol	Test Conditions	Characteristic Values		
		($T_J = 25^\circ\text{C}$, unless otherwise specified)		
		min.	typ.	max.
V_{DSS}	$V_{GS} = 0 \text{ V}$, $I_D = 250 \mu\text{A}$	200		V
$V_{GS(\text{th})}$	$V_{DS} = V_{GS}$, $I_D = 250 \mu\text{A}$	2		V
I_{GSS}	$V_{GS} = \pm 20 \text{ V}_{DC}$, $V_{DS} = 0$		± 100	nA
I_{DSS}	$V_{DS} = 200 \text{ V}$ $V_{DS} = 160 \text{ V}$ $V_{GS} = 0 \text{ V}$	$T_J = 25^\circ\text{C}$ $T_J = 125^\circ\text{C}$	25 250	μA μA
$R_{DS(on)}$	$V_{GS} = 10 \text{ V}$, $I_D = 28 \text{ A}$ Pulse test, $t \leq 300 \mu\text{s}$, duty cycle d $\leq 2 \%$		0.055	Ω

IXYS reserves the right to change limits, test conditions, and dimensions.

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Features

- International standard package JEDEC TO-247 AD
- Low $R_{DS(on)}$ HDMOS™ process
- Rugged polysilicon gate cell structure
- High commutating dv/dt rating
- Fast switching times

Applications

- Switch-mode and resonant-mode power supplies
- Motor controls
- Uninterruptible Power Supplies (UPS)
- DC choppers

Advantages

- Easy to mount with 1 screw (isolated mounting screw hole)
- Space savings
- High power density

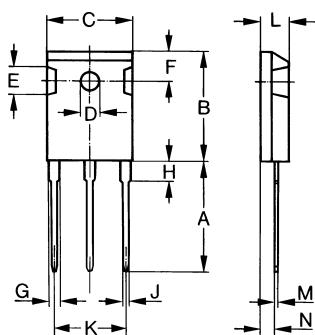
Symbol	Test Conditions	Characteristic Values			
		($T_J = 25^\circ\text{C}$, unless otherwise specified)	min.	typ.	max.
g_{fs}	$V_{DS} = 10 \text{ V}; I_D = 28 \text{ A}$, pulse test	24	34	S	
C_{iss} C_{oss} C_{rss}	$V_{GS} = 0 \text{ V}, V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$	3900		pF	
		760		pF	
		320		pF	
$t_{d(on)}$ t_r $t_{d(off)}$ t_f	$V_{GS} = 10 \text{ V}, V_{DS} = 100 V_{DSS}, I_D = 46 \text{ A}$ $R_G = 4.3 \Omega$ (External)	23		ns	
		30		ns	
		90		ns	
		28		ns	
$Q_{g(on)}$ Q_{gs} Q_{gd}	$V_{GS} = 10 \text{ V}, V_{DS} = 0.5 \cdot V_{DSS}, I_D = 0.5 I_{D25}$	230		nC	
		42		nC	
		110		nC	
R_{thJC}			0.45	K/W	
R_{thCK}			0.24	K/W	

Source-Drain Diode

Characteristic Values
($T_J = 25^\circ\text{C}$, unless otherwise specified)

Symbol	Test Conditions	min.	typ.	max.
I_s	$V_{GS} = 0 \text{ V}$		46	A
I_{SM}	Repetitive; pulse width limited by T_{JM}		180	A
V_{SD}	$I_F = I_s, V_{GS} = 0 \text{ V}$, Pulse test, $t \leq 300 \mu\text{s}$, duty cycle $d \leq 2 \%$		1.8	V
t_{rr}	$I_F = 0.5 I_s, -di/dt = 100 \text{ A}/\mu\text{s}, V_R = 100 \text{ V}$	260	590	ns
Q_{rr}		2.34	7.2	uC

TO-247 AD (IXTH) Outline



Dim.	Millimeter Min.	Millimeter Max.	Inches Min.	Inches Max.
A	19.81	20.32	0.780	0.800
B	20.80	21.46	0.819	0.845
C	15.75	16.26	0.610	0.640
D	3.55	3.65	0.140	0.144
E	4.32	5.49	0.170	0.216
F	5.4	6.2	0.212	0.244
G	1.65	2.13	0.065	0.084
H	-	4.5	-	0.177
J	1.0	1.4	0.040	0.055
K	10.8	11.0	0.426	0.433
L	4.7	5.3	0.185	0.209
M	0.4	0.8	0.016	0.031
N	1.5	2.49	0.087	0.102